

TPS816

Photo-electric Switches

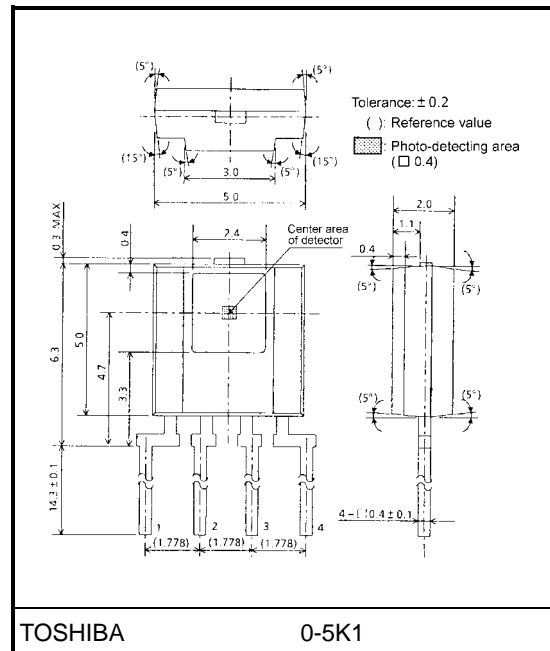
Office Equipment such as Photocopiers, Printers and Fax Machines

Unit: mm

The TPS816 is an Si photo-IC for digital output. It incorporates a photodiode, amp, waveform shaper, LED driver and sync detector in a single chip.

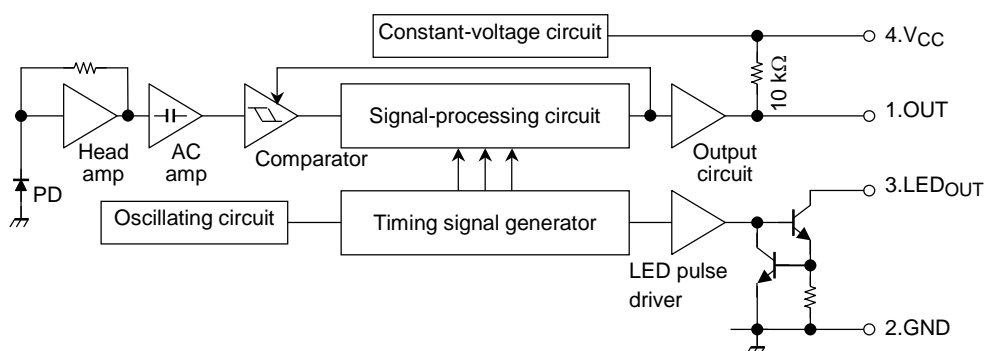
Use of sync optical modulation makes the IC ideal for applications in external light.

- Housed in compact side-view epoxy resin package
- High resistance to external light due to sync optical modulation: $E_X = 3000 \text{ lx (min)}$
- High-sensitivity: $E_{HL} = 1 \text{ } \mu\text{W/mm}^2 \text{ (max)}$
- Wide operating temperature range: $T_{opr} = -30^\circ\text{C to } 85^\circ\text{C}$
- High LED output current and low-level output current:
 $I_{LED} = 70 \text{ mA (Ta = } T_{opr}\text{)}$
 $I_{OL} = 16 \text{ mA (Ta = } T_{opr}\text{)}$
- Digital output (pull-up resistor included) : Low-level output for light input
- TPS816 package resin impermeable to visible light



Weight: g (typ.)

Block Diagram



Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Supply voltage	V _{CC}	7	V
Output voltage	V _{OUT}	≤ V _{CC}	V
Output current (Ta = Topr)	I _{OUT}	16	mA
LED output voltage	V _{LED}	≤ V _{CC}	V
LED pulse forward current (Ta = Topr)	I _{LED}	70	mA
Operating temperature	T _{opr}	−30~85	°C
Storage temperature	T _{stg}	−40~100	°C
Soldering temperature (5s) (Note 1)	T _{sol}	260	°C

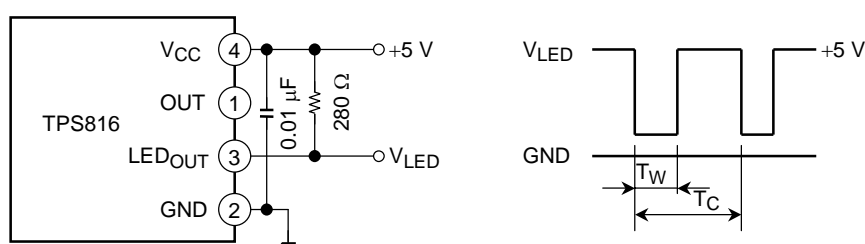
Note 1: Solder under the lead stopper.

Electrical and Optical Characteristics (V_{CC} = 5 V, Ta = 25°C)

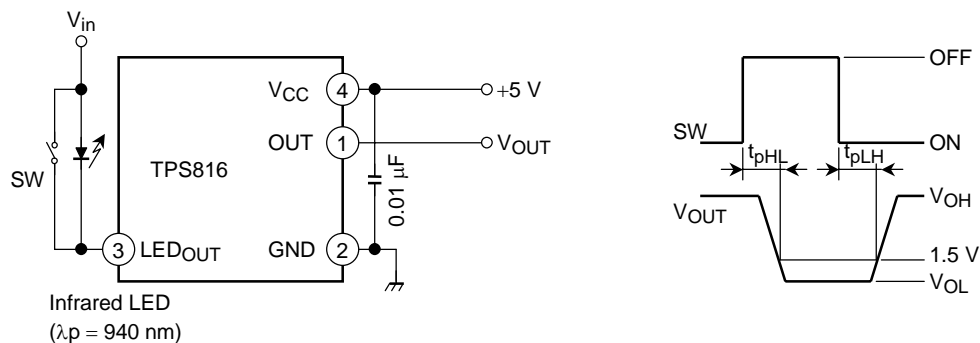
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Supply voltage		V _{CC}	—	4.5	5	5.5	V
Supply current		I _{CC}	V _{OUT} , V _{LED} left open	—	4	7	mA
Output	High-level output voltage	V _{OH}	E = 0	4.9	5	—	V
	Low-level output voltage	V _{OL}	I _{OL} = 16 mA, E = 2 μW/nm ² (Note 2)	—	0.15	0.4	V
LED output	Low-level output voltage	V _{LED}	I _{LED} = 70 mA (peak)	1.05	1.35	1.65	V
	Pulse cycle	T _C	(Note 3)	64	130	220	μs
	Pulse width	T _W	(Note 3)	4	8	13.7	μs
	Duty ratio	T _W /T _C	—	—	6	10	%
Peak sensitivity wavelength		λ _p	—	—	900	—	nm
Propagation characteristics	H → L threshold radiant incidence	E _{HL}	No visible light (Note 2)	—	0.6	1.0	μW/mm ²
	L → H threshold radiant incidence	E _{LH}		—	0.4	0.8	
	Hysteresis	E _{LH} /E _{HL}	—	0.45	0.65	0.8	—
	Propagation delay time (L → H)	t _{pLH}	(Note 4)	—	400	670	μs
	Propagation delay time (H → L)	t _{pHL}		—	400	670	
Permissible luminosity		E _X	E = 2 μW/nm ² (Note 2, 5)	3000	—	—	lx

Note 2: The signal light source is an infrared LED with λ_p = 940 nm.

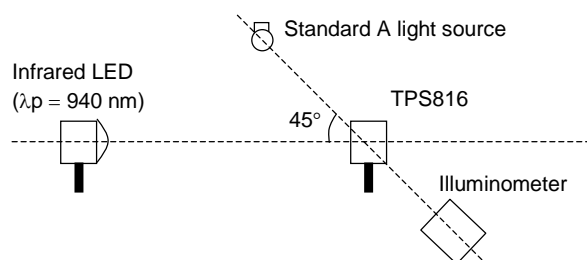
Note 3: The LED output waveform measurement circuit and waveform are as follows:



Note 4: The switching time measurement circuit and waveform are as follows:



Note 5: Measurement of permissible external luminance

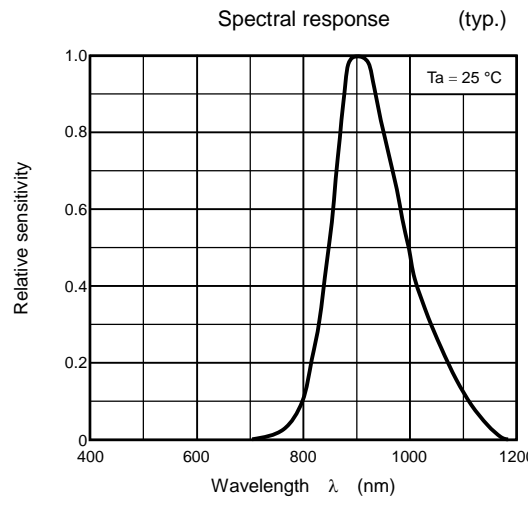
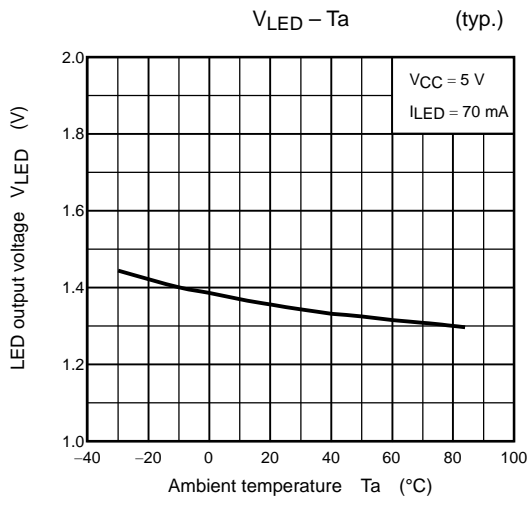
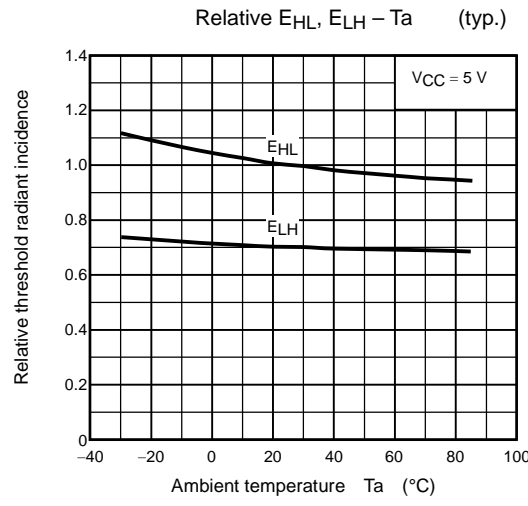
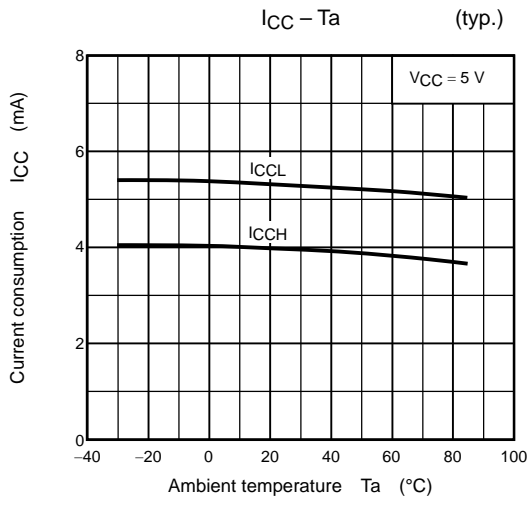
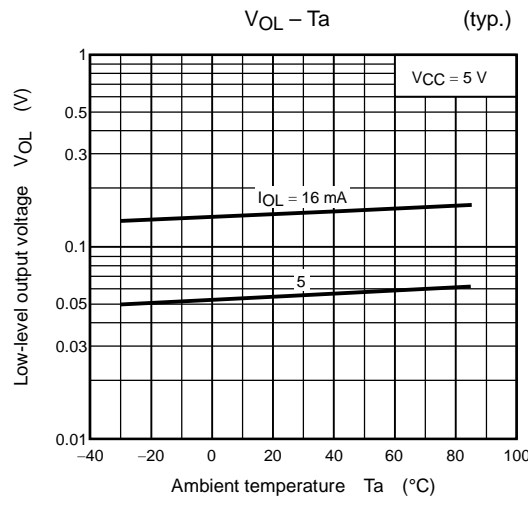
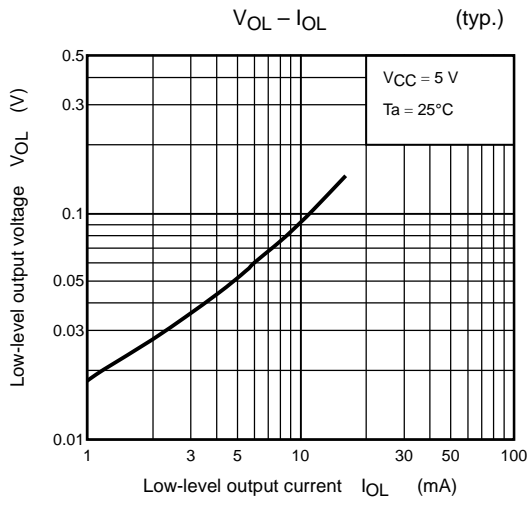


Measure the luminance limit at which the device operates normally.

The light used is a CIE Standard A light source (a standard tungsten bulb with a color temperature of 2856°K).

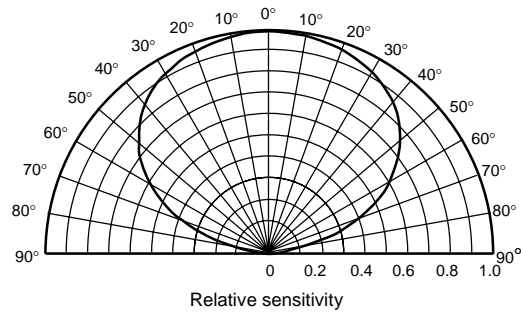
Handling Precautions

- When using the device with an LED, use an infrared LED. Note that light with a wavelength of 800 nm or less cannot be detected.
- Do not use the device in an environment where the external light is 3000 lx or more, as this may prevent the device from working properly.
- At power-on the internal circuit takes about 100 μ s to stabilize. During this period the output signal is unstable and may change. Design the circuit so that no signal is output during this period.
- The photo-IC has a highly sensitive amp built in. To stabilize the power line, insert a bypass capacitor of up to 0.01 μ F between V_{CC} and GND, close to the device.
- If the LED is directly connected to the LEDOUT pin, excessive current will flow in the LED, severely degrading the optical output. Be sure to insert a limiting resistor to prevent excessive current flow in the LED.
- When forming the leads, bend each lead under the lead stopper. Soldering must be performed after the leads have been formed.
- Soldering must be performed under the stopper.



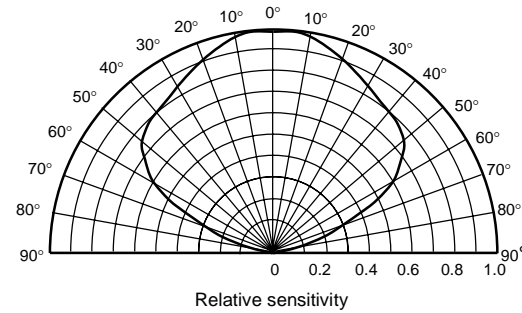
Radiation pattern - vertical direction (typ.)

Ta = 25°C

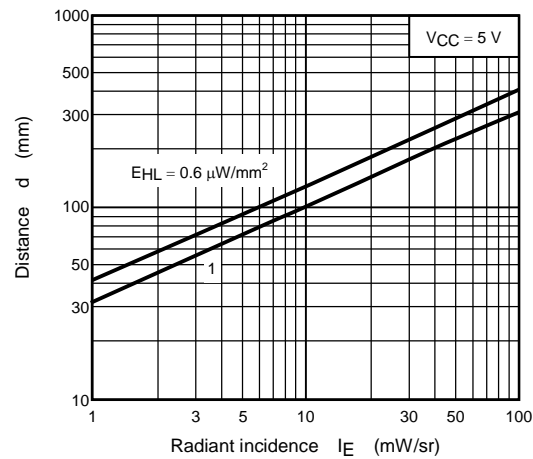


Radiation pattern - horizontal direction (typ.)

Ta = 25°C



$I_E - d$ (typ.)



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